

1                   ABSTRACT OF THE DISCLOSURE

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3     Disclosed is a process for forming fluidic ink  
4     passageways in actuation wafers for novel thermal ink jet  
5     printheads. The process comprises the steps of applying  
6     a thin coating of a heat-curable, photopatternable epoxy  
7     polymer composition to a lower substrate such as a heater  
8     wafer, and drying and photopatterning the coating to form  
9     a patterned, semi-solid adhesive layer. The layer and  
10    supporting substrate are pressed against the surface of a  
11    mating ink inlet substrate to bond the layer to the  
12    surface of the mating substrate without the need for a  
13    separate bonding layer. The present process simplifies  
14    and improves the prior known process by replacing the use  
15    of a photosensitive resin layer and a separate adhesive  
16    bonding layer with a single layer of an epoxy resin  
17    composition which is both photosensitive and adhesive, to  
18    eliminate the need for applying two separate layers and  
19    the concern that said layers have good bonding strength  
20    for their wafers and for each other.